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-continued

$$\begin{aligned} \Rightarrow f(R') &= -h \cdot \exp\{-(R - R_0)/\alpha\} \\ &= -h \cdot \exp\left\{(R - R_0) \cdot \frac{\ln(0.05) \cdot \tan(1.5\theta)}{0.95h}\right\} \end{aligned}$$

Actual curve equation of the contact hole is achieved.

Next, as mentioned above, at the location where the tangent slope of the particular point of the contiguous wall 132 is $\tan \delta$, the light leakage is acceptable, and the contrast ratio of the liquid-crystal display is qualified, and the aperture ratio and the contrast ratio are optimized. The equation of half of the second width of the metal layer along the first direction is:

$$\begin{aligned} \frac{\partial f(R')}{\partial R'} &= \tan \delta = \frac{\partial}{\partial R'} \left\{ -h \cdot \exp \left[R' \cdot \frac{\ln(0.05) \cdot \tan(1.5\theta)}{0.95h} \right] \right\} \quad (7) \\ \Rightarrow -h \cdot \exp \left[R' \cdot \frac{\ln(0.05) \cdot \tan(1.5\theta)}{0.95h} \right] \cdot \frac{\partial}{\partial R'} \left[R' \cdot \frac{\ln(0.05) \cdot \tan(1.5\theta)}{0.95h} \right] &= \tan \delta \\ \Rightarrow \exp \left[R' \cdot \frac{\ln(0.05) \cdot \tan(1.5\theta)}{0.95h} \right] &= \frac{-\tan \delta \cdot 0.95}{\ln(0.05) \cdot \tan(1.5\theta)} \\ \Rightarrow R' \cdot \frac{\ln(0.05) \cdot \tan(1.5\theta)}{0.95h} &= \ln \left[\frac{-\tan \delta \cdot 0.95}{\ln(0.05) \cdot \tan(1.5\theta)} \right] \\ \Rightarrow R' \cdot \frac{0.95h}{\ln(0.05) \cdot \tan(1.5\theta)} \cdot \ln \left[\frac{-\tan \delta \cdot 0.95}{\ln(0.05) \cdot \tan(1.5\theta)} \right] & \\ \Rightarrow R = R_0 + \frac{0.95h}{\ln(0.05) \cdot \tan(1.5\theta)} \cdot \ln \left[\frac{-\tan \delta \cdot 0.95}{\ln(0.05) \cdot \tan(1.5\theta)} \right] & \end{aligned}$$

Considering that ± 3.8 is acceptable manufacturing tolerance, when the first width and the second width satisfy the following equation, the aperture ratio and the contrast ratio are optimized:

$$\begin{aligned} 2 * \left\{ \frac{L_2}{2} + \frac{0.95h}{\ln(0.05) \cdot \tan(1.5\theta)} \cdot \ln \left[\frac{-\tan \delta \cdot 0.95}{\ln(0.05) \cdot \tan(1.5\theta)} \right] \right\} - 3.8 &\leq \\ L_1 \leq 2 * \left\{ \frac{L_2}{2} + \frac{0.95h}{\ln(0.05) \cdot \tan(1.5\theta)} \cdot \ln \left[\frac{-\tan \delta \cdot 0.95}{\ln(0.05) \cdot \tan(1.5\theta)} \right] \right\} + 3.8 & \end{aligned}$$

In one embodiment, to achieve aperture ratio and contrast ratio balanced, the angle δ could be equal to 10 degrees. In another one embodiment, to achieve an improved aperture ratio (transmittance), the angle δ is smaller than 10 degrees, and the angle δ is greater than or equal to 5 degrees (5 degrees $\leq \delta < 10$ degrees). In another one embodiment, to achieve an improved contrast ratio (low light leakage in dark state), the angle δ is greater than 10 degrees, and the angle δ is smaller than or equal to 20 degrees (10 degrees $< \delta \leq 20$ degrees)

With reference to FIG. 2A, the element substrate 100 further comprises a first conductive layer 140 disposed on the planarization layer 130 in the contact region, wherein the first conductive layer 140 is electrically connected to the metal layer 120 via the contact hole 131. The first conductive layer 140 is made of transparent material or metal. In one embodiment, a second conductive layer 141 is disposed on the planarization layer 130 in the pixel region. The second conductive layer 141 can be the same with or different from the first conductive layer 140.

FIG. 2B shows another element substrate of an embodiment of the invention. With reference to FIG. 2B, the metal layer 120 is a source electrode or a drain electrode of a

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driving element (TFT). The metal layer can contact with a semiconductor layer made of polycrystalline silicon, non-crystalline silicon or metal oxide. In one embodiment, the element substrate 100 further comprises a first insulation layer 138, a second insulation layer 139 and a third insulation layer 170. The first insulation layer 138 is located between the metal layer 120 and the substrate 110. The first insulation layer 138 can be made of silicon oxide, silicon nitride, alumina nitride, or other transparent materials. The second insulation layer 139 is located between the metal layer 120 and the planarization layer 130, wherein the contact hole 131 passing through the planarization layer 130 and the second insulation layer 139 to expose the metal layer 120. The material of second insulation layer 139 could be the same with the first insulation layer 138. The third insulation layer 170 is located between the first conductive layer 140 and the planarization layer 130. The material of third insulation layer 170 could be the same with the first insulation layer 138. FIG. 2C shows another element substrate of an embodiment of the invention, wherein the third insulation layer 170 is located between the second conductive layer 141 and the planarization layer 130.

FIG. 3A shows the element substrate of the embodiment of the invention utilized in a liquid-crystal display 200, which comprises an active area A and a peripheral area (B). FIG. 3B shows detailed structures of portion 3B in FIG. 3A, wherein the liquid-crystal display 200 further comprises scan lines 201 (along the first direction X), data lines 202 (along the third direction Y), a semiconductor layer 203, source electrodes 240, a contact hole 231, a hole bottom 233 of the contact hole, drain electrodes 204, common electrodes 205 and pixel electrodes 210, which are located in the active area A. In an embodiment of the invention, the metal layer 120 could be the source electrodes 240, the drain electrodes 204, the scan lines 201 or the signal lines 202. The contact hole 231 defines a contact region, and the pixel region is adjacent to the contact region. FIG. 3C shows the detailed structures of another one embodiment, wherein slits 206 of the pixel electrodes 210 extends along the third direction Y.

With reference to FIG. 2A, in another one embodiment, the metal 120 comprises a first edge 121, the first edge 121 vertically corresponds to a critical point 136 which is on the contiguous wall 132, and the tangent slope of the contiguous wall 132 at the critical point 136 is $\tan \delta$ (5 degrees $\leq \delta \leq 20$ degrees). The base point 135 is located at the point where the contiguous wall 132 is connected to the hole bottom 133. The straight line L connects a reference point 134 and a base point 135. An included angle θ is between a straight line L and a horizontal line. The metal layer 120 has a first width L1 along the first direction X, and the hole bottom 133 of the contact hole 131 has a second width L2 along the first direction X, wherein the first width and the second width satisfy the following equation:

$$2 * \left\{ \frac{L_2}{2} + \frac{(1-p)h}{\ln(p) \cdot \tan(1.5\theta)} \cdot \ln \left[\frac{-\tan \delta * (1-p)}{\ln(p) \cdot \tan(1.5\theta)} \right] \right\} = L_1$$

L1 is the first width of the metal layer 120 along the first direction X, and L2 is the second width of the hole bottom 133 of the contact hole 131 along the first direction X, and p is an adjustable parameter, and $0 < p \leq 0.1$. By modifying the parameters above, the curvature and the shape of the contiguous wall 132 can be modified.

In the embodiments above, the contact hole is in the active area A. However, the invention is not limited thereby. The